

Hyper CHIPLED

LW Q98A



Vorläufige Daten / Preliminary Data

Besondere Merkmale

- **Gehäusetyp:** 0603
- **Besonderheit des Bauteils:** kleinste Bauform für Anwendungen mit wenig Platzbedarf
- **Farbort:** $x = 0,30$, $y = 0,33$ nach CIE 1931 (weiß)
- **Typische Farbtemperatur:** 7200 K
- **Farbwiedergabeindex:** 80
- **Abstrahlwinkel:** extrem breite Abstrahlcharakteristik (160°)
- **Technologie:** GaN
- **optischer Wirkungsgrad:** 2 lm/W
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 8-mm Gurt mit 4000/Rolle, ø180 mm

Anwendungen

- Einkopplung in Lichtleiter
- Flache Hinterleuchtung (LCD, Handy, Schalter, Display)
- Spielsachen

Features

- **package:** 0603
- **feature of the device:** smallest package for applications where small space is required
- **color coordinates:** $x = 0.30$, $y = 0.33$ acc. to CIE 1931 (white)
- **typ. color temperature:** 7200 K
- **color reproduction index:** 80
- **viewing angle:** extremely wide (160°)
- **technology:** GaN
- **optical efficiency:** 2 lm/W
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 8-mm tape with 4000/reel, ø180 mm

Applications

- coupling into light guides
- flat backlighting (LCD, cellular phones, switches, displays)
- toys

Typ Type	Emissions-farbe Color of Emission	Farbe der Lichtaustritts-fläche Color of the Light Emitting Area	Lichtstärke Luminous Intensity $I_F = 10 \text{ mA}$ $I_v (\text{mcd})$	Bestellnummer Ordering Code	
			min.	typ.	
LW Q98A	white	colored diffused	7.1	15	Q62702-P5185

Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 11\%$ ermittelt.
 Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of $\pm 11\%$.

Anm.: Farbselektiert nach Farbortgruppen (siehe Seite 5)

Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur 3 bzw. 4 Halbgruppen besteht. Einzelne Halbgruppen sind nicht erhältlich.
 In einer Verpackungseinheit / Gurt ist immer nur eine Halbgruppe enthalten.

Note: Color selection acc. to Chromaticity coordinate groups (see page 5)

The standard shipping format for serial types includes a lower or upper family group of 3 or 4 individual groups. Individual half groups are not available.
 No packing unit / tape ever contains more than one luminous intensity half group.

Grenzwerte**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebstemperatur Operating temperature range	T_{op}	- 30 ... + 85	°C
Lagertemperatur Storage temperature range	T_{stg}	- 40 ... + 85	°C
Sperrschichttemperatur Junction temperature	T_j	+ 95	°C
Durchlassstrom Forward current	I_F	15	mA
Stoßstrom Surge current $t \leq 10 \mu\text{s}, D = 0.1$	I_{FM}	0.1	A
Sperrspannung Reverse voltage	V_R	5	V
Leistungsaufnahme Power consumption	P_{tot}	70	mW
Wärmewiderstand Thermal resistance Sperrsicht/Umgebung Junction/ambient	$R_{th JA}$	700	K/W
Sperrsicht/Lötpad Junction/solder point	$R_{th JS}$	400	K/W

Kennwerte ($T_A = 25^\circ\text{C}$)

Characteristics

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Farbkoordinate x nach CIE 1931 ¹⁾ Chromaticity coordinate x acc. to CIE 1931 $I_F = 10 \text{ mA}$	x	0.30	—
Farbkoordinate y nach CIE 1931 ¹⁾ Chromaticity coordinate y acc. to CIE 1931 $I_F = 10 \text{ mA}$	y	0.33	—
Abstrahlwinkel bei 50 % I_V (Vollwinkel) Viewing angle at 50 % I_V	2ϕ	160	Grad deg.
Durchlassspannung ²⁾ Forward voltage $I_F = 10 \text{ mA}$	V_F V_F	3.5 4.1	V V
Sperrstrom Reverse current $V_R = 5 \text{ V}$	I_R I_R	0.01 10	μA μA
Temperaturkoeffizient von x Temperature coefficient of x $I_F = 10 \text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	TC_x	0.07	$10^{-3}/\text{K}$
Temperaturkoeffizient von y Temperature coefficient of y $I_F = 10 \text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	TC_y	0.25	$10^{-3}/\text{K}$
Temperaturkoeffizient von V_F Temperature coefficient of V_F $I_F = 10 \text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	TC_V	-3.1	mV/K
Optischer Wirkungsgrad Optical efficiency $I_F = 10 \text{ mA}$	η_{opt}	2	lm/W

¹⁾ Farbortgruppen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 0,01$ ermittelt.
Chromaticity coordinate groups are tested at a current pulse duration of 25 ms and a tolerance of ± 0.01 .

²⁾ Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von $\pm 0,1 \text{ V}$ ermittelt.
Voltages are tested at a current pulse duration of 1 ms and a tolerance of $\pm 0.1 \text{ V}$.

¹⁾ Farbortgruppen
Chromaticity coordinate groups

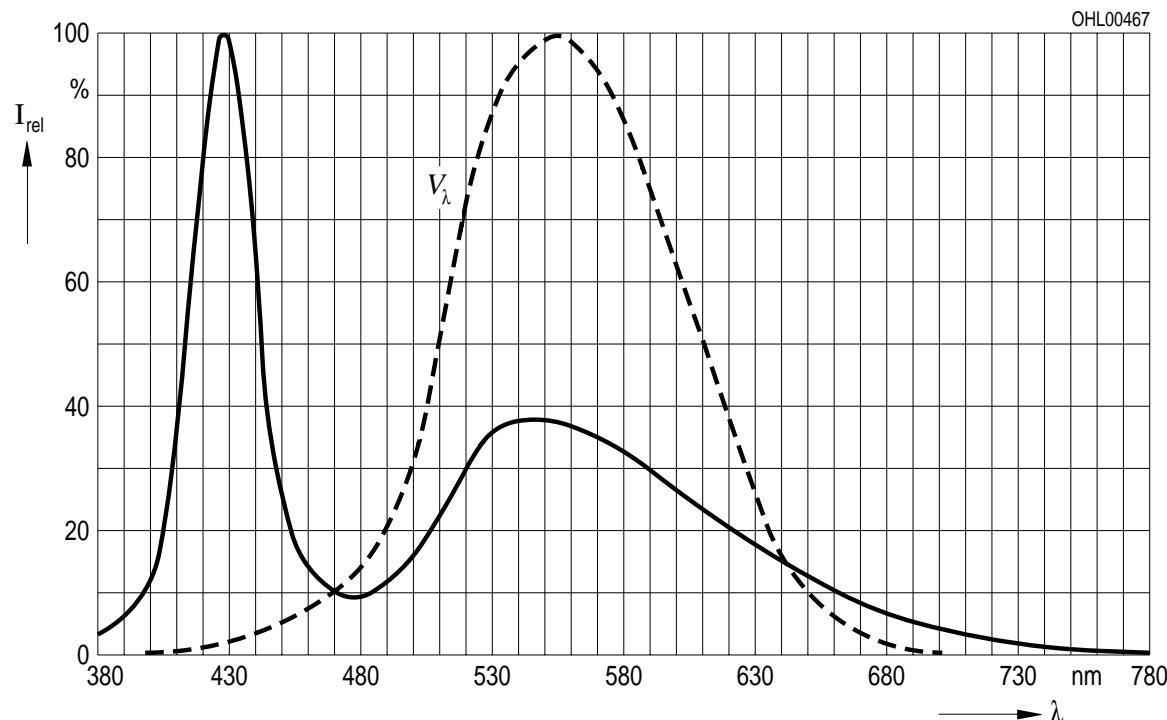
Gruppe Group	x		y	
	min.	max.	min.	max.
A	0.265	0.305	0.250	0.360
B	0.305	0.345	0.300	0.410

Relative spektrale Emission $I_{\text{rel}} = f(\lambda)$, $T_A = 25^\circ \text{C}$, $I_F = 10 \text{ mA}$

Relative Spectral Emission

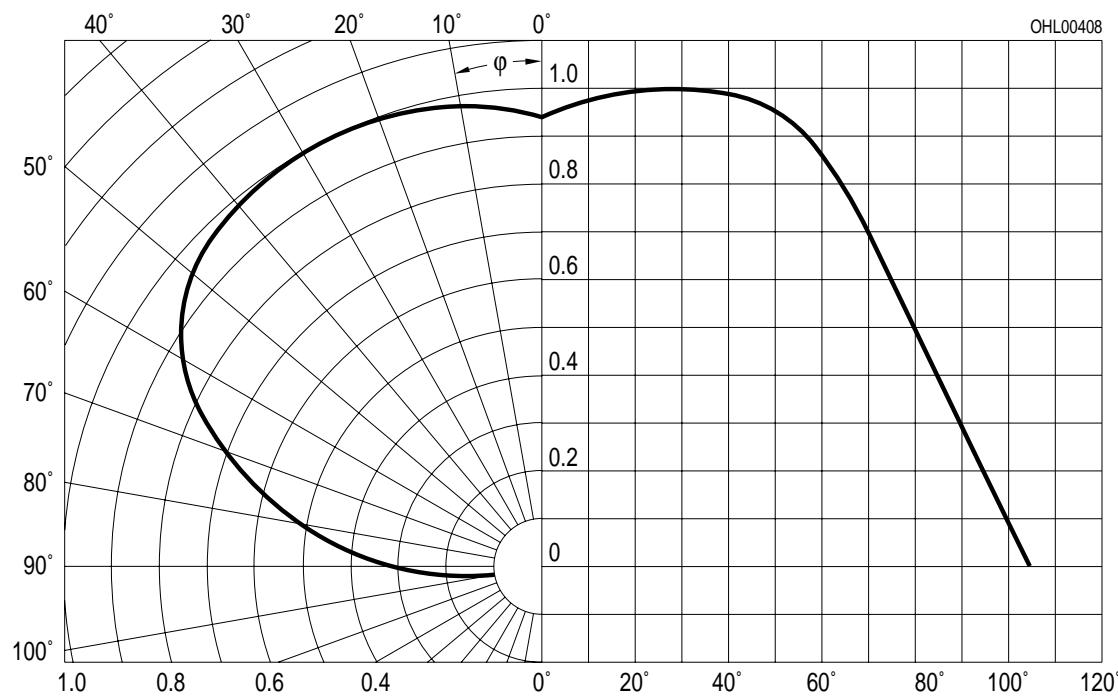
$V(\lambda) = \text{spektrale Augenempfindlichkeit}$

Standard eye response curve



Abstrahlcharakteristik $I_{\text{rel}} = f(\phi)$

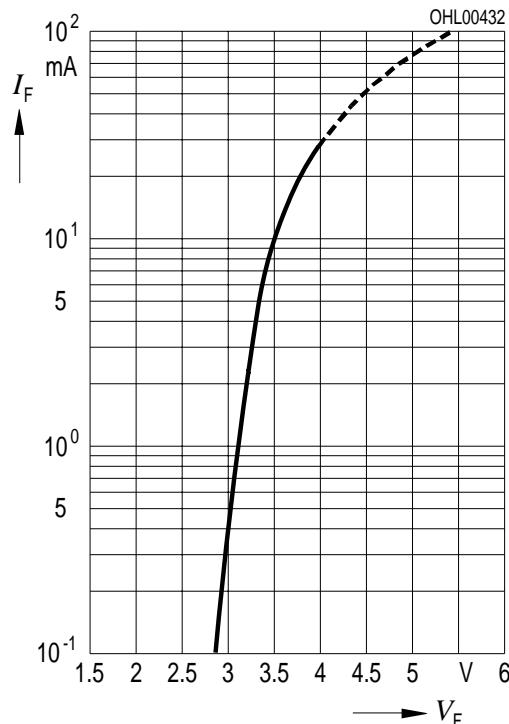
Radiation Characteristic



Durchlassstrom $I_F = f(V_F)$

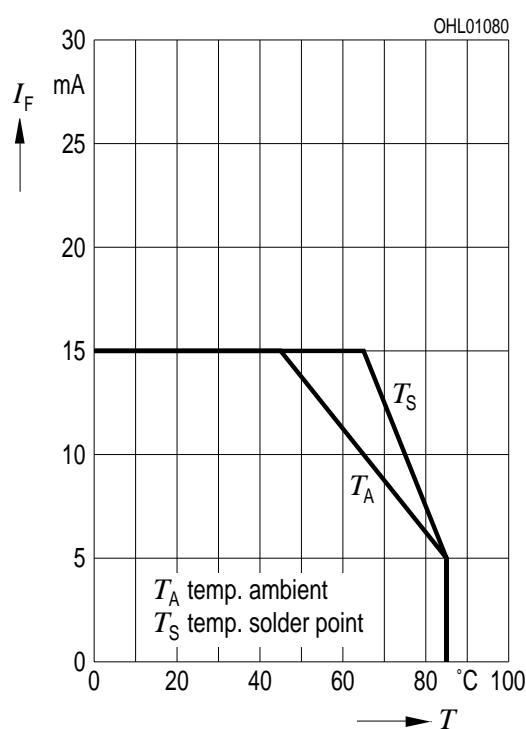
Forward Current

$T_A = 25^\circ\text{C}$



Maximal zulässiger Durchlassstrom $I_F = f(T)$

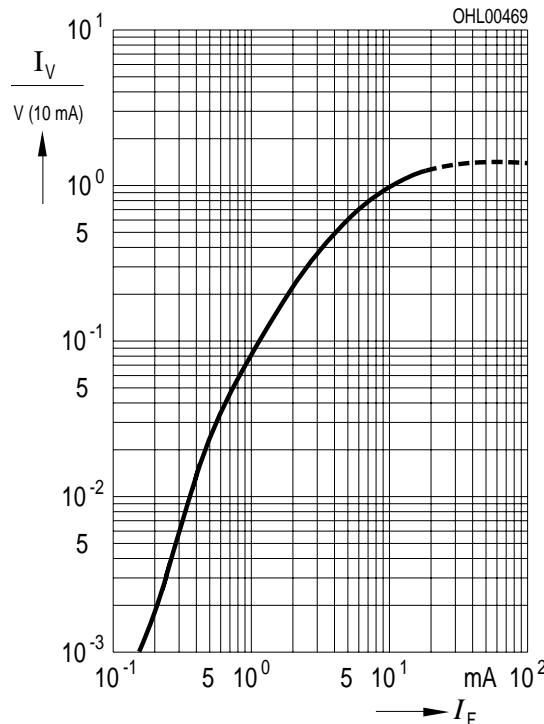
Max. Permissible Forward Current



Relative Lichtstärke $I_V/I_{V(10 \text{ mA})} = f(I_F)$

Relative Luminous Intensity

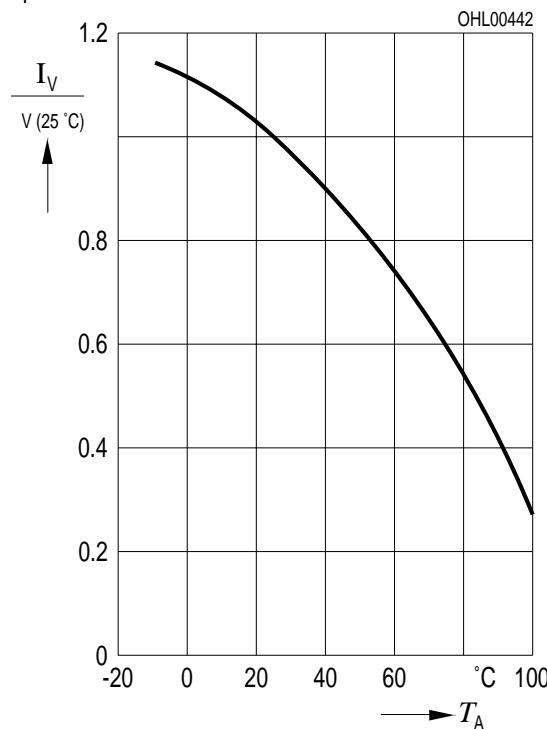
$T_A = 25^\circ\text{C}$

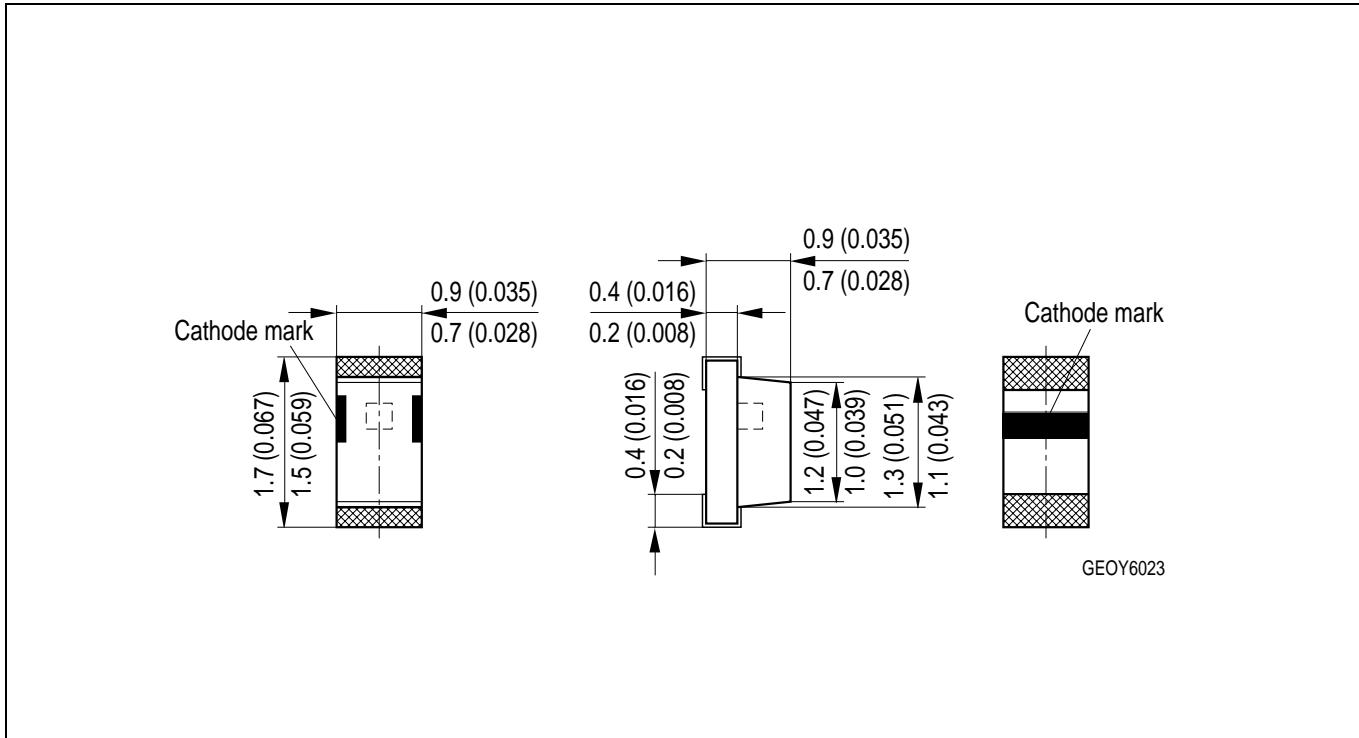


Relative Lichtstärke $I_V/I_{V(25^\circ\text{C})} = f(T_A)$

Relative Luminous Intensity

$I_F = 10 \text{ mA}$



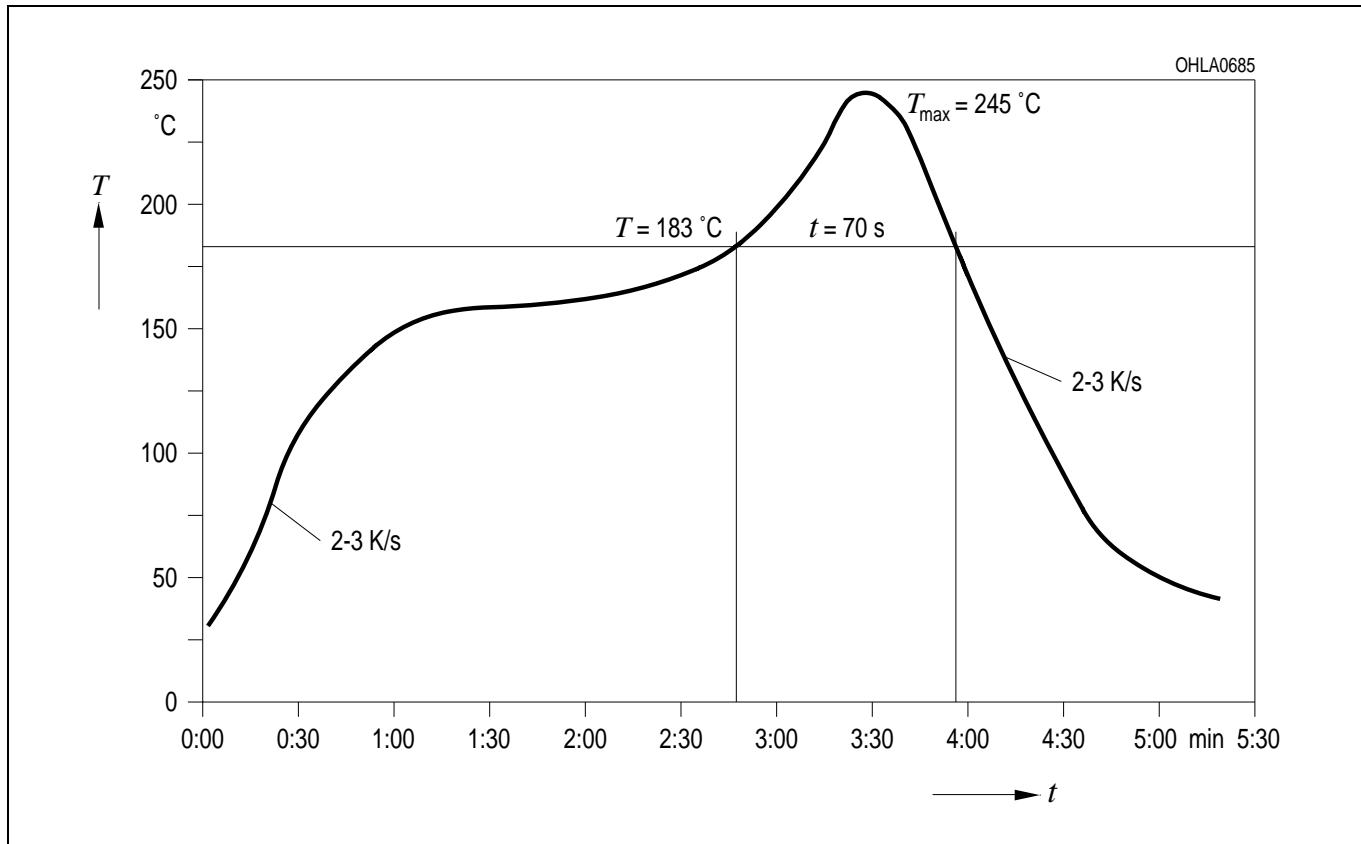
**Maßzeichnung
Package Outlines**

Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

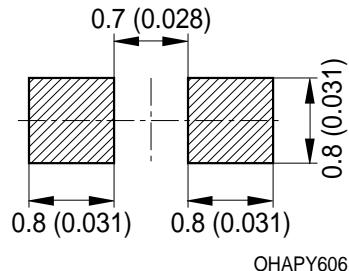
Gewicht / Approx. weight: 1.4 mg

Lötbedingungen Vorbehandlung nach JEDEC Level 2
Soldering Conditions Preconditioning acc. to JEDEC Level 2

IR-Reflow Lötprofil (nach IPC 9501)
IR Reflow Soldering Profile (acc. to IPC 9501)



Empfohlenes Lötpaddesign IR Reflow Löten
Recommended Solder Pad IR Reflow Soldering

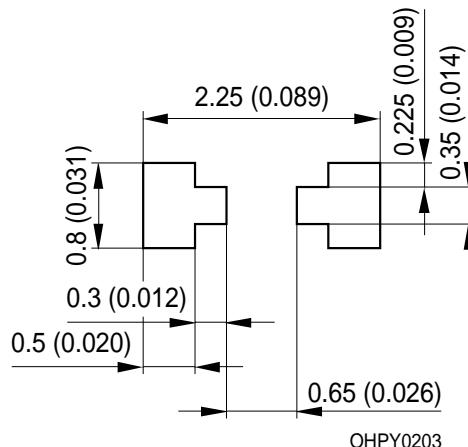


OHAPY606

Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Empfohlenes Lötpaddesign verwendbar für Hyper CHIPLED und Chipled - Bauform 0603
IR Reflow Löten

Recommended Solder Pad useable for Hyper CHIPLED and Chipled - Package 0603
IR Reflow Soldering



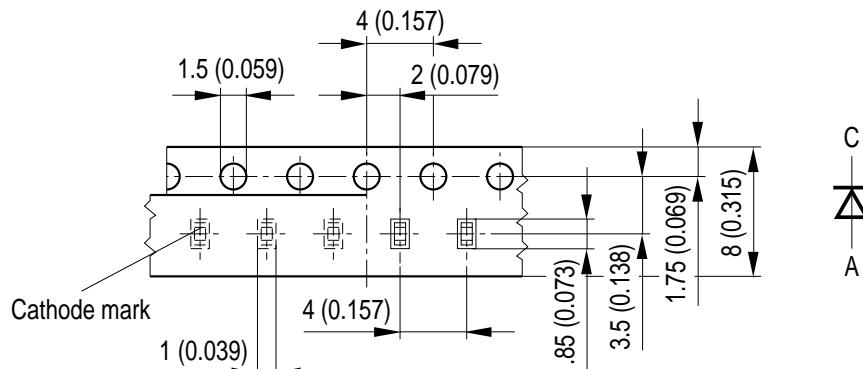
OHPY0203

Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).
Empfohlene Lötpastendicke: 120 µm/ recommended thickness of solder paste: 120 µm

Gurtung / Polarität und Lage**Method of Taping / Polarity and Orientation**

Verpackungseinheit 4000/Rolle, ø180 mm

Packing unit 4000/reel, ø180 mm



OHAY0531

Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2001-11-30

Previous Version: 2001-03-07

Page	Subjects (major changes since last revision)
10	recommended solder pad

Patent List

Patent No.

US 6 066 861, US 6 277 301

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